

## 100V N-Channel MOSFETs

### General Description

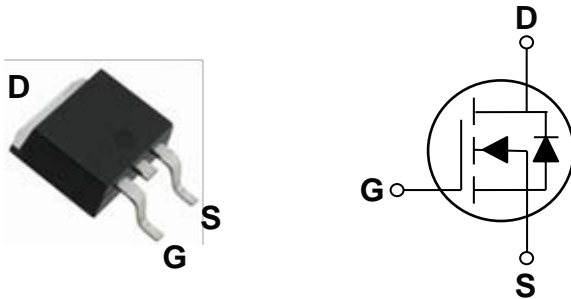
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
100V	115mΩ	12A

### Features

- 100V, 12A, R<sub>DS(ON)</sub>=115mΩ@V<sub>GS</sub>=10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### TO252 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	12	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	7.6	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	48	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	6	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	11	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	34.7	W
	Power Dissipation – Derate above 25°C	0.27	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	3.1	°C/W



# FTK0956D

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Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.09	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=10A$	---	95	115	m $\Omega$
		$V_{GS}=4.5V, I_D=8A$	---	100	125	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5	---	$\text{mV}/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=2A$	---	8.7	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=50V, V_{GS}=10V, I_D=2A$	---	20	40	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	3.2	6	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	3.6	7	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=1A$	---	18	36	ns
$T_r$	Rise Time <sup>3,4</sup>		---	4	8	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	40	80	
$T_f$	Fall Time <sup>3,4</sup>		---	3	6	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	1400	2800	pF
$C_{oss}$	Output Capacitance		---	60	120	
$C_{rss}$	Reverse Transfer Capacitance		---	35	70	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	2	4	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	12	A
$I_{SM}$	Pulsed Source Current		---	---	24	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time <sup>3</sup>	$I_S=1A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	38	---	ns
$Q_{rr}$	Reverse Recovery Charge <sup>3</sup>		---	27	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=11A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

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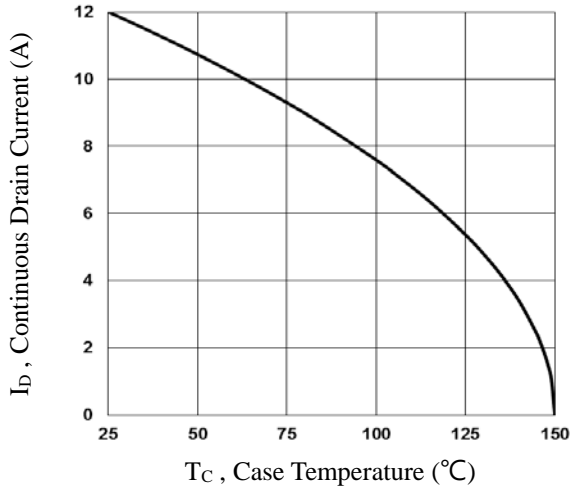


Fig.1 Continuous Drain Current vs.  $T_C$

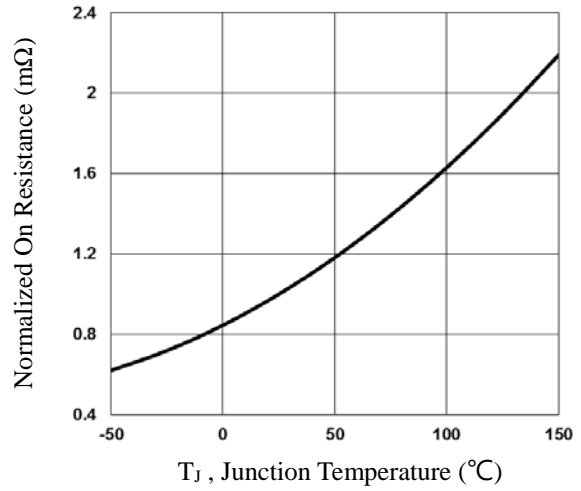


Fig.2 Normalized RDSON vs.  $T_J$

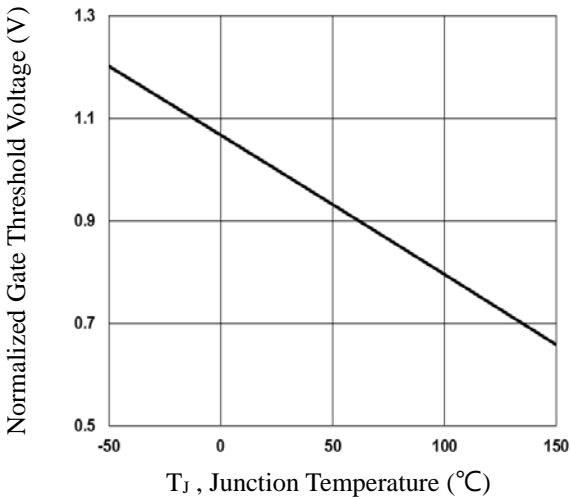


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

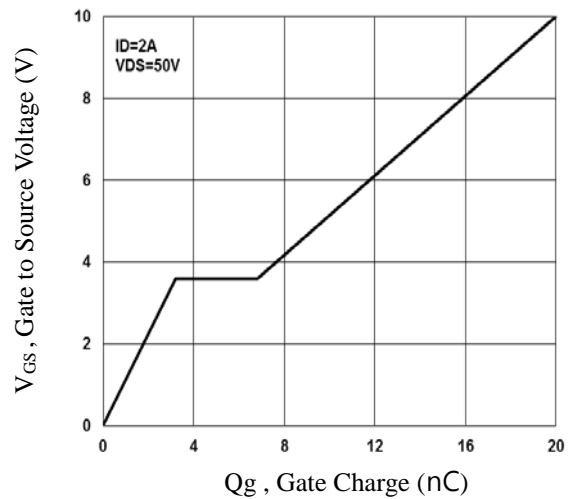


Fig.4 Gate Charge Waveform

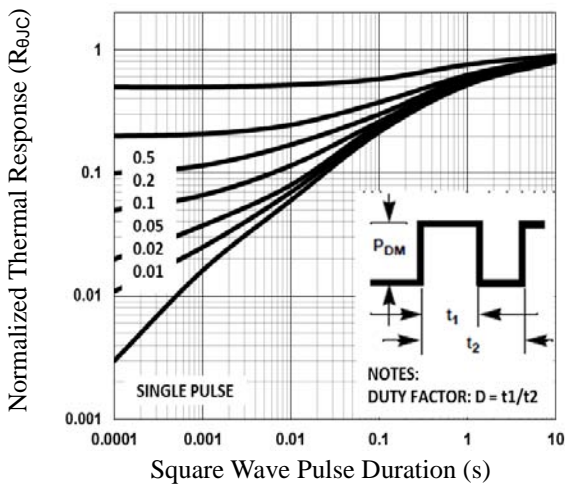


Fig.5 Normalized Transient Impedance

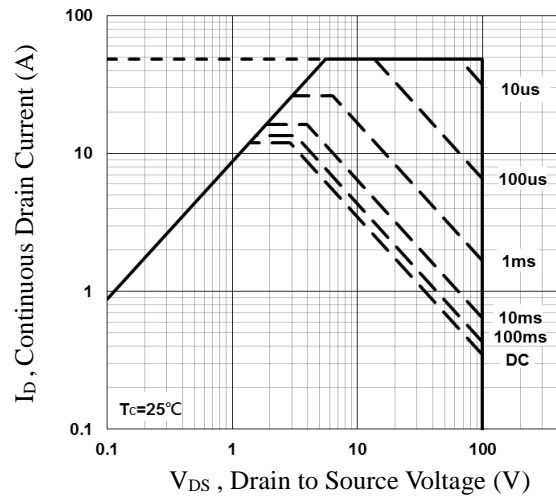


Fig.6 Maximum Safe Operation Area

## 100V N-Channel MOSFETs

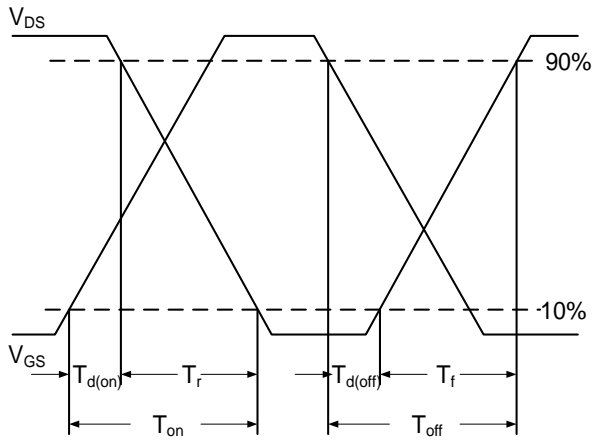


Fig.7 Switching Time Waveform

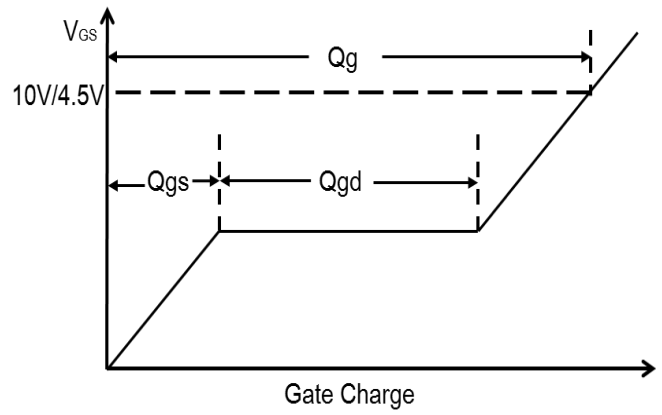
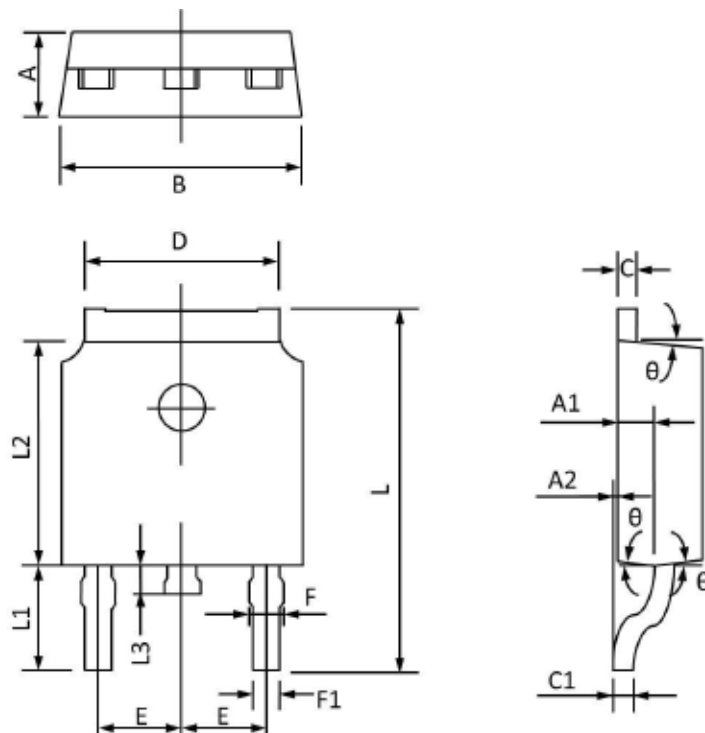


Fig.8 Gate Charge Waveform

## 100V N-Channel MOSFETs

### TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	1.140	0.600	0.045	0.024
F1	0.880	0.500	0.035	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.223	5.400	0.245	0.213
L3	1.200	0.600	0.047	0.024
$\theta$	9°	3°	9°	3°